

Technical Specifications

SERVICE AND SUPPORT

1-year and 3-year limited warranties and 90-day software limited warranty options depending on country. Batteries have a default one-year limited warranty except for HP Long Life batteries which will follow the one or three year warranty of the platform. Refer to <http://www.hp.com/support/batterywarranty/> for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: <http://www.hp.com/go/cpc>.⁴²

42. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit <http://www.hp.com/go/cpc>. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Technical Specifications

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	19 V
	Average Operating Power	5.71 w
	Integrated Graphics	AMD
	Max Operating Power	UMA < 45W
Temperature	Operating	41° to 95° F (5° to 35° C)
	Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	Operating	10% to 90%, non-condensing
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	Operating	40 G, 2 ms, half-sine
	Non-operating	200 G, 2 ms, half-sine
Random Vibration	Operating	0.75 grms
	Non-operating	1.50 grms
Altitude (unpressurized)	Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
	Non-operating	-50 to 10,000 ft (-15.24 to 3,048 m)
Planned Industry Standard Certifications	UL	Yes
	CSA	Yes
	FCC Compliance	Yes
	ENERGY STAR®	Yes, Select models ⁴³
	EPEAT®	Yes, Gold in U.S. ⁴⁴
	ICES	Yes
	Australia	Yes
	NZ A-Tick Compliance	Yes
	CCC	Yes
	Japan VCCI Compliance	Yes
	KC	Yes
	BSMI	Yes
	CE Marking Compliance	Yes
	BNCI or BELUS	Yes
	CIT	Yes
	EAC	Yes
Saudi Arabian Compliance (ICCP)	Yes	
SABS	Yes	
UKRSERTCOMPUTER	Yes	

43. Configurations of the HP ProBook x360 435 G7 G8 that are ENERGY STAR® qualified are identified as HP ProBook x360 435 G8 ENERGY STAR on HP websites and on <http://www.energystar.gov>.

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44. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit www.epeat.net for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

1. Actual brightness will be lower with touchscreen or Sure View.

Panel LCD 13.3 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45% NTSC 250 nits eDP 1.2 w/o PSR slim	Outline Dimensions (W x H x D)	300.56 x 187.77 mm (max) (w/ PCB & w/o bracket)
	Active Area	293.76 x 165.24 mm (typ.)
	Weight	260 g (max)
	Diagonal Size	13.3 inch
	Thickness	3.0 mm (max)
	Interface	eDP 1.2 (2 lane)
	Surface Treatment	BrightView Glass
	Touch Enabled	Yes
	Contrast Ratio	600:1 (typ.)
	Refresh Rate	60 Hz
	Brightness¹	250nits (typ.)
	Pixel Resolution	1920 x 1080 (FHD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
Color Gamut Coverage	45% NTSC	
Color Depth	6 bits	
Viewing Angle	UWVA 85/85/85/85	

QuickSpecs

HP ProBook x360 435 G8 Notebook PC

Technical Specifications

Panel LCD 13.3 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 72% NTSC 400 nits eDP 1.4+PSR2 ultraslim	Outline Dimensions (W x H x D)	299.06 x 185.54 mm (max)
	Active Area	293.76 x 165.24 mm (typ.)
	Weight	170 g (max)
	Diagonal Size	13 inch
	Thickness	2.0 mm (max)
	Interface	eDP 1.4 + PSR2 (2 lane)
	Surface Treatment	BrightView Glass
	Touch Enabled	Yes
	Contrast Ratio	1200:1 (typ.)
	Refresh Rate	60 Hz
	Brightness¹	400 nits
	Pixel Resolution	1920 x 1080 (FHD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	72% NTSC
	Color Depth	8 bits
Viewing Angle	UWVA 85/85/85/85	

QuickSpecs

HP ProBook x360 435 G8 Notebook PC

Technical Specifications

Panel LCD 13.3 inch diagonal FHD (1920 x 1080) BrightView WLED UWVA 72% NTSC 1000 nits eDP 1.4+PSR2 flat Privacy NWBZ	Outline Dimensions (W x H x D)	298.76 x 186.04 mm (typ.)
	Active Area	293.76 x 165.24 mm (typ.)
	Weight	255 g (max)
	Diagonal Size	13.3 inch
	Thickness	3.0 mm (max)
	Interface	eDP 1.4 + PSR2
	Surface Treatment	BrightView Glass
	Touch Enabled	Yes
	Contrast Ratio	2000:1 (typ.)
	Refresh Rate	60 Hz
	Brightness¹	1000 nits
	Pixel Resolution	1920 x 1080(FHD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	72% NTSC
	Color Depth	8 bit
Viewing Angle	UWVA 85/85/85/85	

Technical Specifications

STORAGE

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

128 GB 2280 M2 PCIe NVMe TLC Solid State Drive	Form Factor	M.2 2280
	Capacity	128 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe
	Maximum Sequential Read	1300~2047MB/s
	Maximum Sequential Write	800~1200MB/s
	Logical Blocks	250,069,680
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; DIPM; TRIM; DEVSLP

256 GB 2280 PCIe NVMe Value Solid State Drive	Form Factor	M.2 2280
	Capacity	256 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe
	Maximum Sequential Read	Around 1500 ~ 1700 MB/s
	Maximum Sequential Write	Around 780 ~ 1300 MB/s
	Logical Blocks	500118192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2

QuickSpecs

HP ProBook x360 435 G8 Notebook PC

Technical Specifications

SSD 512 GB 2280 M2 PCIe-3x4 SS NVMe TLC

Form Factor	M.2 2280
Capacity	512 GB
NAND Type	TLC
Height	0.09 in (2.3 mm)
Width	0.87 in (22 mm)
Weight	0.02 lb (10 g)
Interface	PCIe NVMe Gen3X4
Maximum Sequential Read	Around 2700 ~ 3400 MB/s
Maximum Sequential Write	Around 1390 ~ 2956 MB/s
Logical Blocks	1000215215
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security; TRIM; L1.2

SSD 512 GB 2280 PCIe NVMe Value

Form Factor	M.2 2280
Capacity	512 GB
NAND Type	TLC/QLC
Height	0.09 in (2.3 mm)
Width	0.87 in (22 mm)
Weight	0.02 lb (10 g)
Interface	PCIe NVMe
Maximum Sequential Read	Around 1500 ~ 1700 MB/s
Maximum Sequential Write	Around 860 ~ 1500 MB/s
Logical Blocks	1000215215
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security; TRIM; L1.2

QuickSpecs

HP ProBook x360 435 G8 Notebook PC

Technical Specifications

SSD 1TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided	Form Factor	M.2 2280
	Capacity	1 TB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	3100 ~ 3500 MB/s
	Maximum Sequential Write	2770 ~ 3037 MB/s
	Logical Blocks	2000409264
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2

Technical Specifications

NETWORKING/COMMUNICATIONS

Realtek RTL8822CE 802.11ac 2x2 Wi-Fi® and Bluetooth® 5.0¹	Wireless LAN Standards	IEEE 802.11a	
		IEEE 802.11b	
		IEEE 802.11g	
		IEEE 802.11n	
		IEEE 802.11ac	
		IEEE 802.11d	
		IEEE 802.11e	
		IEEE 802.11h	
		IEEE 802.11i	
		IEEE 802.11k	
		IEEE 802.11r	
		IEEE 802.11v	
		Interoperability	Wi-Fi certified
		Frequency Band	•802.11b/g/n 2.402 – 2.482 GHz •802.11a/n/ac 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
Data Rates	•802.11b: 1, 2, 5.5, 11 Mbps •802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) •802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)		
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
Security³	•IEEE 64 / 128 bit WEP encryption for a/b/g mode only •AES-CCMP: 128 bit in hardware •802.1x authentication •WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. •WPA2 certification •WPA3 certification •IEEE 802.11i •WAPI		
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points		

QuickSpecs

HP ProBook x360 435 G8 Notebook PC

Technical Specifications

Output Power²	<ul style="list-style-type: none">• 802.11b: +18.5dBm minimum• 802.11g: +17.5dBm minimum• 802.11a: +18.5dBm minimum• 802.11n HT20(2.4GHz): +15.5dBm minimum• 802.11n HT40(2.4GHz): +14.5dBm minimum• 802.11n HT20(5GHz): +15.5dBm minimum• 802.11n HT40(5GHz): +14.5dBm minimum• 802.11ac VHT80(5GHz): +11.5dBm minimum• 802.11ac VHT160(5GHz): +11.5dBm minimum
Power Consumption	<ul style="list-style-type: none">• Transmit mode: 2.0 W• Receive mode: 1.6 W• Idle mode (PSP)180 mW (WLAN Associated)• Idle mode: 50 mW (WLAN unassociated)• Connected Standby/Modern Standby: 10mW• Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity⁴	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g
Operating Voltage	3.3 v +/- 9%
Temperature	Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)

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Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF	
	LED OFF – Radio ON	

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary. Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies

Technical Specifications

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2

Headset Profile (HSP)

Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.
 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
 3. Check latest software/driver release for updates on supported security features.
 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
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Intel® Wi-Fi 6 AX200 and Bluetooth® 5.0 (802.11 ax 2 x 2, supporting gigabit data rate) non-vPro^{1,5}

Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Wi-Fi certified
Frequency Band	•802.11b/g/n/ax 2.402 – 2.482 GHz •802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
Data Rates	•802.11b: 1, 2, 5.5, 11 Mbps •802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) •802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz) • 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security³	•IEEE 64 / 128 bit WEP encryption for a/b/g mode only •AES-CCMP: 128 bit in hardware •802.1x authentication •WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. •WPA2 certification •IEEE 802.11i •WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)

Technical Specifications

Roaming	IEEE 802.11 compliant roaming between access points
Output Power²	<ul style="list-style-type: none">• 802.11b: +18.5dBm minimum• 802.11g: +17.5dBm minimum• 802.11a: +18.5dBm minimum• 802.11n HT20(2.4GHz): +15.5dBm minimum• 802.11n HT40(2.4GHz): +14.5dBm minimum• 802.11n HT20(5GHz): +15.5dBm minimum• 802.11n HT40(5GHz): +14.5dBm minimum• 802.11ac VHT80(5GHz): +11.5dBm minimum• 802.11ac VHT160(5GHz): +11.5dBm minimum• 802.11ax HT40(2.4GHz): +10dBm minimum• 802.11ax VHT160(5GHz): +10dBm minimum
Power Consumption	<ul style="list-style-type: none">• Transmit mode: 2.0 W• Receive mode: 1.6 W• Idle mode (PSP)180 mW (WLAN Associated)• Idle mode: 50 mW (WLAN unassociated)• Connected Standby/Modern Standby: 10mW• Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity⁴	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ax, MCS11(HT40): -59dBm maximum 802.11ax, MCS11(VHT160): -58.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	<ol style="list-style-type: none">1. Type 2230: 2.3 x 22.0 x 30.0 mm2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	<ol style="list-style-type: none">1. Type 2230: 2.8 g2. Type 126: 1.3 g
Operating Voltage	3.3 v +/- 9%

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Temperature	Operating	14° to 158° F (–10° to 70° C)
	Non-operating	–40° to 176° F (–40° to 80° C)
Humidity	Operating	10% to 90% (non-condensing)
	Non-operating	5% to 95% (non-condensing)
Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF LED OFF – Radio ON	

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)
	BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps
	BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps

[1. Actual throughput may vary.](#)

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mW
Peak (Rx) 230 mW
Selective Suspend 17 mW

Bluetooth Software Supported Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management Certifications ETS 300 328, ETS 300 826
Low Voltage Directive IEC950
UL, CSA, and CE Mark

Bluetooth Profiles Supported BT4.1-ESR 5/6/7 Compliance
LE Link Layer Ping
LE Dual Mode
LE Link Layer
LE Low Duty Cycle Directed Advertising
LE L2CAP Connection Oriented Channels

Technical Specifications

Train Nudging & Interlaced Scan
BT4.2 ESR08 Compliance
LE Secure Connection- Basic/Full
LE Privacy 1.2 –Link Layer Privacy
LE Privacy 1.2 –Extended Scanner Filter Policies
LE Data Packet Length Extension
FAX Profile (FAX)
Basic Imaging Profile (BIP)2
Headset Profile (HSP)
Hands Free Profile (HFP)
Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.
 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
 3. Check latest software/driver release for updates on supported security features.
 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
 5. Wi-Fi 5 or 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.
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Technical Specifications

Intel® 9260

802.11a/b/g/n/ac (2 x 2) Wireless LAN Standards Wi-Fi® and Bluetooth® 5 Combo¹ (Non-vPro)

- IEEE 802.11a
- IEEE 802.11b
- IEEE 802.11g
- IEEE 802.11n
- IEEE 802.11ac
- IEEE 802.11d
- IEEE 802.11e
- IEEE 802.11h
- IEEE 802.11i
- IEEE 802.11k
- IEEE 802.11r
- IEEE 802.11v

Interoperability

Wi-Fi certified

Frequency Band

- 802.11b/g/n
2.402 – 2.482 GHz
- 802.11a/n/ac
4.9 – 4.95 GHz (Japan)
5.15 – 5.25 GHz
5.25 – 5.35 GHz
5.47 – 5.725 GHz
5.825 – 5.850 GHz

Data Rates

- 802.11b: 1, 2, 5.5, 11 Mbps
- 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
- 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)

Modulation

Direct Sequence Spread Spectrum
BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security³

- IEEE 64 / 128 bit WEP encryption for a/b/g mode only
- AES-CCMP: 128 bit in hardware
- 802.1x authentication
- WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
- WPA2 certification
- WPA3 certification
- IEEE 802.11i
- WAPI

Network Architecture Models

Ad-hoc (Peer to Peer)
Infrastructure (Access Point Required)

Roaming

IEEE 802.11 compliant roaming between access points

Technical Specifications

Output Power²	<ul style="list-style-type: none">• 802.11b: +18.5dBm minimum• 802.11g: +17.5dBm minimum• 802.11a: +18.5dBm minimum• 802.11n HT20(2.4GHz): +15.5dBm minimum• 802.11n HT40(2.4GHz): +14.5dBm minimum• 802.11n HT20(5GHz): +15.5dBm minimum• 802.11n HT40(5GHz): +14.5dBm minimum• 802.11ac VHT80(5GHz): +11.5dBm minimum• 802.11ac VHT160(5GHz): +11.5dBm minimum
Power Consumption	<ul style="list-style-type: none">• Transmit mode: 2.0 W• Receive mode: 1.6 W• Idle mode (PSP)180 mW (WLAN Associated)• Idle mode: 50 mW (WLAN unassociated)• Connected Standby/Modern Standby: 10mW• Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity⁴	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g
Operating Voltage	3.3 v +/- 9%
Temperature	Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)

Technical Specifications

Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF	
	LED OFF – Radio ON	

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full

Technical Specifications

LE Privacy 1.2 –Link Layer Privacy
LE Privacy 1.2 –Extended Scanner Filter Policies
LE Data Packet Length Extension
FAX Profile (FAX)
Basic Imaging Profile (BIP)2
Headset Profile (HSP)
Hands Free Profile (HFP)
Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.
 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
 3. Check latest software/driver release for updates on supported security features.
 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
-

QuickSpecs

HP ProBook x360 435 G8 Notebook PC

Technical Specifications

POWER

HP 45 W USB type C Straight 1.8 m AC Adapter	Dimensions	94.0 mm x 40.0 mm x 26.5 mm
	Weight	192.5 g +/- 10 g (Not including power cord. Power cord varies by country)
	Input	Input Efficiency Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 12V: 87.41% 15V: 87.8%
		Input frequency range 47 ~ 63 Hz
		Input AC current Max. 1.4 A at 90 VAC
	Output	Output power 5V/15W 9V/27W 12V/36W 15V/45W
		DC output 5V / 9V / 12V / 15V
		Hold-up time 5ms at 115 Vac input
		Output current limit < 5.0A
	Connector	USB Type-C™
	Environmental Design	Operating temperature 32° to 95° F (0° to 35° C) Non-operating (storage) temperature -4° to 185° F (-20° to 85° C) Altitude 0 to 16,400 ft (0 to 5000m) Humidity 20% to 95% Storage Humidity 10% to 95%
	EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.

HP 45 W Smart AC adapter	Dimensions	3.74 x 1.57 x 1.04 in (9.5 x 4.0 x 2.65 cm)
	Weight	0.386 lb (175g) max (Not including power cord. Power cord varies by country)
	Input	90 to 265 VAC
		Input Efficiency 87.74% at 115Vac and 88.4% at 230Vac
		Input frequency range 47 ~ 63 Hz
		Input AC current 1.4 A at 90 VAC
	Output	Output power 45 W
		DC output 19.5 V
		Hold-up time 5ms at 115 Vac input
		Output current limit <8.0A
	Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords

QuickSpecs

HP ProBook x360 435 G8 Notebook PC

Technical Specifications

Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
	Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

AC Adapter 45 Watt Smart nPFC Standard Barrel 4.5 mm Right Angle 1.8 m 2prong	Dimensions	95.0 x 40.0 x 26.5 mm	
	Weight	200 g +/- 10 g (Not including power cord. Power cord varies by country)	
	Input	Input Efficiency	87.74% at 115Vac and 88.4% at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	1.4 A at 90 VAC
	Output	Output power	45 W
		DC output	19.5 V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<8.0A
	Connector	C6	
Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)	
	Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)	
	Altitude	0 to 16,400 ft (0 to 5000m)	
	Humidity	20% to 95%	
	Storage Humidity	10% to 95%	
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.		

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Technical Specifications

AC Adapter 65 Watt nPFC Standard USB Type-C Straight 1.8 m	Dimensions	90.0 x 51 x 28.5 mm	
	Weight	250 g +/- 10 g (Not including power cord. Power cord varies by country)	
	Input	Input Efficiency 81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A	
	Output	Input frequency range	47 ~ 63 Hz
		Input AC current	1.6 A at 90 VAC and maximum load
		Output power	65 W
		DC output	5V/9V/12V/15V/20V
		Hold-up time	5ms at 115 Vac input
	Connector	Output current limit	<8.0A MAXIMUM
		USB Type-C™	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
Humidity		20% to 95%	
EMI and Safety Certifications	Storage Humidity	10% to 95%	
	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards -IEC60950, EN60950, UL60950, UL62368, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.		

AC Adapter 65 Watt Smart nPFC EM Barrel 4.5 mm New EM	Dimensions	102 x 55 x 30 mm	
	Weight	250 g +/- 10 g (Not including power cord. Power cord varies by country)	
	Input	Input Efficiency 88.0 % at 115 Vac and 89.0 % at 230Vac	
	Output	Input frequency range	47 ~ 63 Hz
		Input AC current	1.7 A at 90 Vac
		Output power	65 W
		DC output	19.5 V
		Hold-up time	5ms at 115 Vac input
	Connector	Output current limit	<11.0 A
		C6	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
Humidity		20% to 95%	
	Storage Humidity	10% to 95%	

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Technical Specifications

EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, UL62368, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.
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AC Adapter 65 Watt Smart nPFC Standard Barrel 4.5 mm Right Angle 1.8 m	Dimensions	90.0 x 51 x 28.5 mm	
	Weight	230 g +/- 10 g (Not including power cord. Power cord varies by country)	
	Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	1.7 A at 90 Vac
	Output	Output power	65 W
		DC output	19.5 V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<11.0 A
	Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
Altitude		0 to 16,400 ft (0 to 5000m)	
Humidity		20% to 95%	
	Storage Humidity	10% to 95%	
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.		

Battery SX 3 Cell 45 Wh Long Life -PL Fast Charge	Dimensions (H x W x L)	184.62 x 85.25 x 6.15 mm	
	Weight	0.195 kg Max	
	Cells/Type	3cell Lithium-Ion Polymer cell	
	Energy	Voltage	13.2V / 11.55V (13.2V / 11.4V)
		Amp-hour capacity	3.9 Ah / 3.75 Ah (3.95 Ah / 3.79 Ah)
		Watt-hour capacity	45 Wh
	Temperature	Operating (Charging)	32° to 113° F (0° to 45° C)
		Operating (Discharging)	14° to 122° F (-10° to 60° C)
	Optional Travel Battery Available	No	
	Warranty	Based on system offering	

Technical Specifications

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- US Federal Energy Management Program (FEMP)
- EPEAT[®] Gold registered in the United States. See <http://www.epeat.net> for registration status in your country.
- TCO 8.0
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label*

Sustainable Impact Specifications

- 35% post-consumer recycled plastic
- External Power Supply 90% Efficiency
- Low halogen
- Outside Box and corrugated cushions are 100% sustainably sourced and recyclable
- Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable
- Recycled Plastic cushions
- Bulk packaging available

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a “Typically Configured Notebook”.

Energy Consumption (in accordance with US ENERGY STAR® test method)

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Sort idle)	5.68 W	5.85 W	5.73 W
Normal Operation (Long idle)	0.81 W	0.83 W	0.79 W
Sleep	0.81 W	0.83 W	0.79 W
Off	0.22 W	0.25 W	0.22 W

QuickSpecs

HP ProBook x360 435 G8 Notebook PC

Technical Specifications

Note:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	19 BTU/hr	20 BTU/hr	20 BTU/hr
Normal Operation (Long idle)	3 BTU/hr	3 BTU/hr	3 BTU/hr
Sleep	3 BTU/hr	3 BTU/hr	3 BTU/hr
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)	Sound Pressure (L_{pAm}, decibels)
Typically Configured – Idle	2.6	15.4
Fixed Disk – Random writes	2.6	15.4
Optical Drive – Sequential reads	4.1	20.7

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the spare parts are available throughout the warranty period and or for up to “5” years after the end of production.

Technical Specifications

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product is 94.1% recycle-able when properly disposed of at end of life.

Packaging Materials

External:	PAPER/Corrugated	256g
Internal:	PAPER/Molded pulp	171 g
	PLASTIC/Polyethylene low density	14 g
	PLASTIC/polypropylene	3

The plastic packaging material contains at least 0% recycled content.

The corrugated paper packaging materials contains at least 61.7% recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see [HP RoHS position statement](#).

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes

Technical Specifications

- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: <http://www.hp.com/go/reuse-recycle> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: <http://www.hp.com/go/recyclers>. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP, Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

<http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html>

Eco-label certifications

<http://www8.hp.com/us/en/hp-information/environment/ecolabels.html>

ISO 14001 certificates:

<http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842>

and

<http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf>

QuickSpecs

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Technical Specifications

footnotes

- Percentage of ocean-bound plastic contained in each component varies by product
- Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
- External power supplies, WWAN modules, power cords, cables and peripherals excluded.
- 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
- Fiber cushions made from 100% recycled wood fiber and organic materials.
- Plastic cushions are made from >90% recycled plastic.

COUNTRY OF ORIGIN

China

Options and Accessories (sold separately and availability may vary by country)

Type	Description	Part #
Cases	HP Essential Top Load Case	H2W17AA
	HP Essential Backpack (up to 15.6")	H1D24AA
Docking	HP USB-C Mini Dock	1PM64AA
	HP Thunderbolt Dock 120W G2	2UK37AA
	HP TB Dock G2 w/ Combo Cable	3TR87AA
	HP TB Dock 120W G2 w/Audio	3YE87AA
	HP TB Dock 120W G2 cable	3XB94AA
	HP TB Dock G2 combo cable	3XB96AA
	HP TB Dock 120W G2 Cable	3XB94AA
	HP TB Dock G2 Combo Cable	3XB96AA
	HP TB Dock G2 Audio Module	3AQ21AA
	HP USB-C/A Universal Dock G2	5TW13AA
	HP USB-C Dock G5	5TW10AA
Input/Output	HP Comfort Grip Wireless Mouse	H2L63AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP USB Fingerprint Mouse	4TS44AA
	HP USB-C to DP	N9K78AA
	HP USB-C to USB-A Hub	Z6A00AA
	HP Elite USB-C Multi Port Hub	4WX89AA
	HP Pro Pen	8JU62AA
HP USB-C to RJ45 Adapter	V7W66AA	
Power	HP 45W Smart AC Adapter 4.5mm	H6Y88AA
	HP 65W Smart AC Adapter 4.5mm	H6Y89AA
	HP 45W LC USB-C Power Adapter	1MZ01AA
	HP 65W LC USB-C Power Adapter	TBD
	USB-C NB Power Bank	1TZ86AA
	HP Essential Power Bank	3TB55AA
Storage	HP External USB Optical Drive	F2B56AA
Memory	HP 4GB DDR4 3200 Memory	286H5AA
	HP 8GB DDR4 3200 Memory	286H8AA
	HP 16GB DDR4 3200 Memory	286J1AA

QuickSpecs

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Options and Accessories (sold separately and availability may vary by country)

Security	HP Sure Key Cable Lock	6UW42AA
	HP Nano Keyed Cable Lock	1AJ39AA

QuickSpecs

HP ProBook x360 435 G8 Notebook PC

Summary of Changes

Date of change:	Version History:	Updated	Description of change:
February 10, 2021	V1 to V2		Processor specs and Environmental Data
March 9, 2021	V2 to V3	Removed	USB-C to RJ45 Adapter
March 17, 2021	V3 to V4	Updated	Environmental Data
March 19, 2021	V4 to V5	Updated	Processor section
April 20, 2021	V5 to V6	Updated	Memory Section and Input/ Output Section Updated
May 6, 2021	V6 to V7	Updated	TPM 2.0/Added HP Smart Support
May 27, 2021	V7 to V8	Updated	HP Pro Security Edition to HP Wolf Pro Security Edition

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